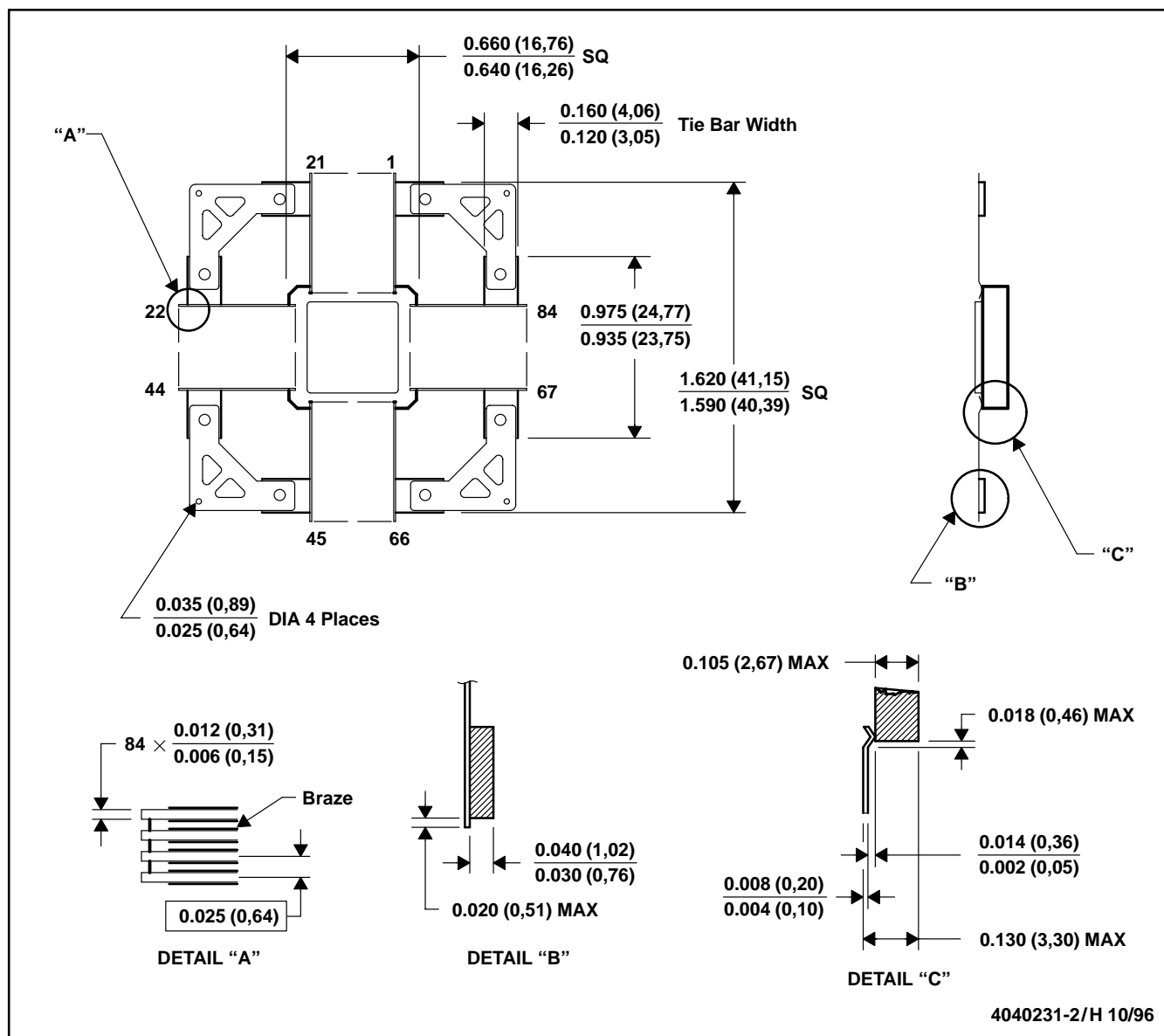


HFG (S-CQFP-F84)

CERAMIC QUAD FLATPACK WITH TIE BAR



- NOTES:
- All linear dimensions are in inches (millimeters).
 - This drawing is subject to change without notice.
 - Ceramic quad flatpack with flat leads brazed to nonconductive tie bar carrier.
 - This package can be hermetically sealed with a metal lid.
 - The terminals are gold plated.

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